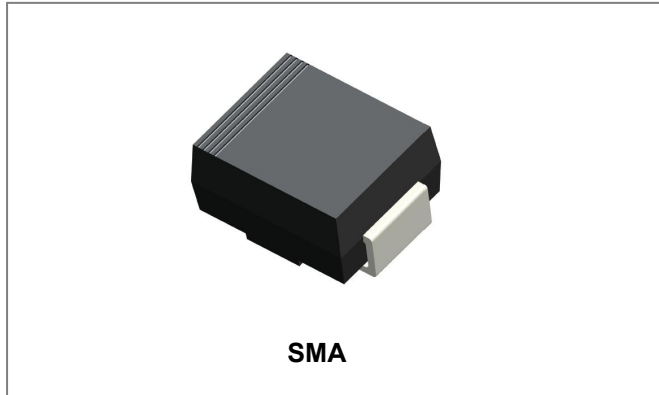


1SMA4753-A SURFACE MOUNT ZENER DIODE



Features

- Glass Passivated Die Construction
- 1.0W Power Dissipation
- 36V Nominal Zener Voltage
- 5% Standard Vz Tolerance
- Low Inductance
- Typical IR Less Than 5.0 μ A Above 11V
- Plastic Case Material has UL Flammability Classification Rating 94V-0
- ROHS Compliant
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request
- "-A" suffix is for Automotive qualified

Circuit Diagram



Mechanical Data

- Case: SMA molded plastic body
- Terminals: Solder Plated, Solderable per MIL-STD-202, Method 208
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Weight: 0.06 grams

Maximum Ratings@T_A=25°C unless otherwise specified

Parameter	Symbol	Value	Units
Power Dissipation (Note 1) Derate Above 25°C	P _D	1.0 8.0	W mW/°C
Forward Voltage @ I _F = 200mA	V _F	1.2	V
Typical Thermal resistance junction to Ambient (Note 1)	R _{θJA}	120	°C/W
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-65 to + 175	°C

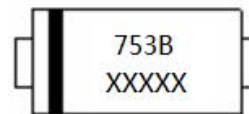
Notes: 1. Valid provided that device terminals are kept at ambient temperature

Ordering Information

Device	Package	Shipping
1SMA4753-A	SMA (Pb-Free)	5000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram



Where XXXXX is YYWWL

753B = Marking Code
YY = Year
WW = Week
L = Lot Number

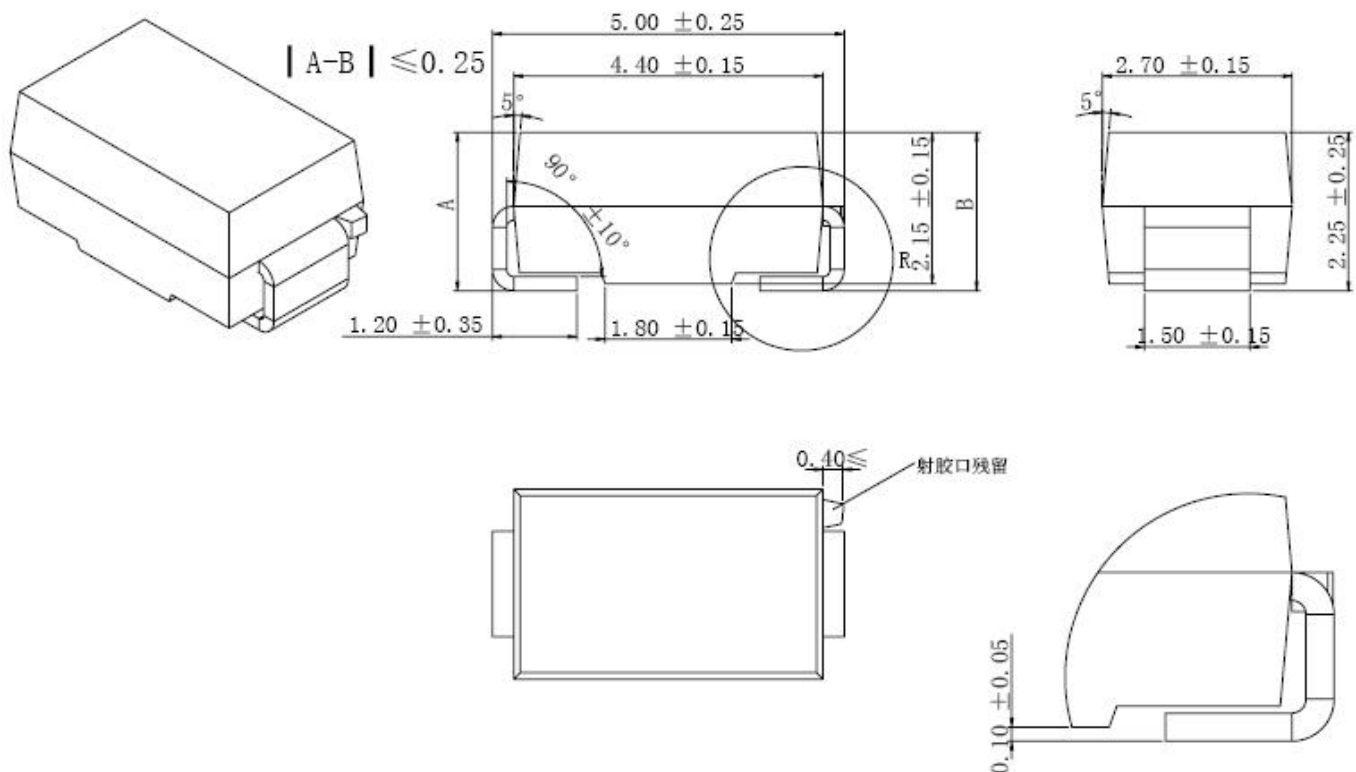
Cautions: Molding resin
Epoxy resin UL:94V-0

Ratings and Characteristics Curves

Device	Marking Code	Nominal Zener Voltage ①	Test Current	Zener Impedance			Leakage Current		Max. Surge Current 8.3ms
		$V_Z @ I_{ZT}$	I_{ZT}	Max. $Z_{ZT} @ I_{ZT}$	Max. $Z_{ZK} @ I_{ZK}$	@ I_{ZK}	Max. $I_R @ V_R$		I_{ZS}
		Volts	mA	Ω	Ω	mA	μA	Volts	mA
1SMA4753	753B	36	7	50	1000	0.25	5	27.4	125

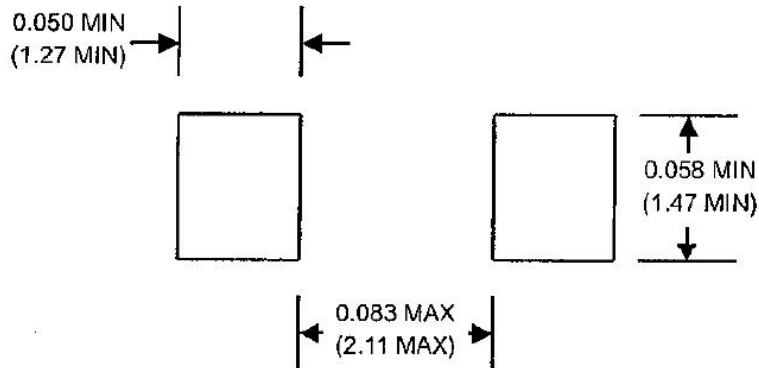
Note: ① V_Z Tolerance is $\pm 5\%$.

Mechanical Dimensions SMA (Millimeters)

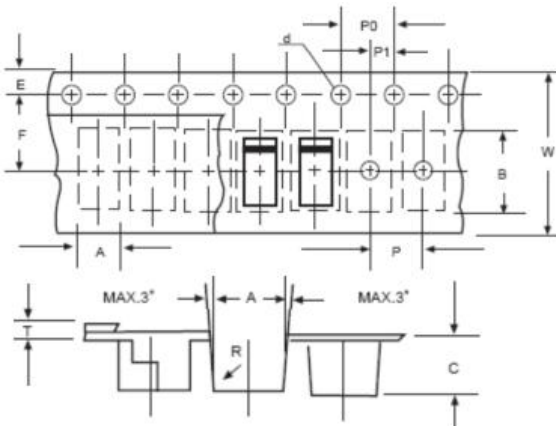


Note: The typical height of the SMA package is 2.25 mm.

Recommended Footprint (Inches/Millimeters)



Carrier Tape Specification SMA



SYMBOL	Millimeters	
	Min.	Max.
A	2.97	3.17
B	5.70	5.90
C	2.32	2.52
d	1.40	1.60
E	1.40	1.60
F	5.60	5.70
P	3.90	4.10
P0	3.90	4.10
P1	1.90	2.10
T	0.25	0.35
W	11.80	12.20

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